

**REMARKS**

Reconsideration of the present application is respectfully requested.

Claims 1, 3-6, 8 and 9 stand rejected under 35 USC 102(b) as being allegedly anticipated by AAPA as shown in FIGs. 5 and 6 and as discussed in the Background section of the present application. The applicants respectfully request that this rejection be withdrawn for the following reasons.

A detailed overview of the presently claimed invention was provided in the Amendment filed on February 9, 2006.

The Examiner should note that independent claims 1 and 6 have been amended to further clarify the distinguishing features of the claimed pressure sensor; namely, that: (1) the case is directly attached to the outer wall of the intake system module; and (2) the interposed member is entirely disposed between an inner wall of the case and the outer surface of the mold resin so as to allow the pressure introduction inlet to communicate with the pressure introduction hole without air leakage.

Referring to FIG. 6 and the paragraph beginning on page 2, line 16, as noted in the previous remarks in the Amendment filed on February 9, 2006, AAPA relies on a hose (10) inserted into a hose insertion bore (11a) and connected to a pressure introduction pipe (13b). Such a conventional structure has a high cost both in additional process and materials associated with mounting the sensor IC (13), connecting the hose (10), and providing the pressure introduction pipe (13b). In addition, vibration can cause the hose (10) to impinge on the edge of the hose insertion bore (11a) and can thus crack and break (page 3, line 6). Further, vibration is coupled directly to the sensor IC (13) causing contact failure between the terminal (13c) and the solder (12a) (page 3, line 9). The primary disadvantages of the AAPA structure are directly

related to the configuration of the hose (10) coupled to the pipe (13b), and are addressed by the present invention as noted on page 4, lines 9-14.

AAPA does not include a case in which the sensor IC and the board are accommodated, and that is directly attached to the outer wall of the intake system module, as does the pressure sensor recited in claims 1 and 6. The pressure sensor as recited in claims 1 and 6 eliminates the need for the rubber hose (10) required by AAPA and therefore eliminates the above-discussed disadvantages attributable to the rubber hose (10).

In addition, the pressure sensor as recited in claims 1 and 6 does not include an interposed member including a resilient member such as the hose (10). Rather, the claimed interposed member has a communication hole, and, unlike the conventional structure of AAPA, is disposed entirely *between an inner wall of a case and an outer surface of a mold resin* so as to allow the pressure introduction inlet to communicate with a pressure introduction hole without air leakage.

Applicants again note that the term “interposed” can be defined as that which is inserted or introduced between other parts. The hose (10) of AAPA clearly extends through the case (11) and thus does not amount to an interposing member and is not disposed between an inner wall thereof and an outer surface of a mold resin.

Nonetheless, in an effort to further prosecution, claims 1 and 6 have been amended to recite that the interposed member is entirely disposed between an inner wall of the case and the outer surface of the mold resin. Therefore, claims 1 and 6 now clearly distinguish the claimed pressure sensor from AAPA, as the rubber hose (10) in AAPA clearly is not entirely disposed between an inner wall of the case and the outer surface of the mold resin.

Claims 3-5, by virtue of depending from claim 1, are allowable for at least the reasons set forth hereinabove with regard to claim 1. Claims 8 and 9, by virtue of depending from claim 6,

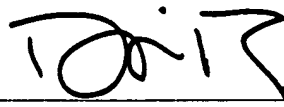
are allowable for at least the reasons set forth hereinabove with regard to claim 6. It is therefore respectfully requested that the rejection of claims 3-5, 8 and 9 be reconsidered and withdrawn.

Claims 2 and 7 stand rejected under 35 USC 103(a) as being allegedly unpatentable over AAPA in view of Morino. However, claims 2 and 7 are allowable over the art of record based on their respective dependencies from claims 1 and 6. Therefore, it is respectfully requested that the Examiner's rejection of claims 2 and 7 be withdrawn.

In view of the foregoing, the applicants respectfully submit that this application is in condition for allowance. A timely notice to that effect is respectfully requested. If questions relating to patentability remain, the examiner is invited to contact the undersigned by telephone.

Please charge any unforeseen fees that may be due to Deposit Account No. 50-1147.

Respectfully submitted,



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